

Welcome to E-XFL.COM

What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "<u>Embedded -</u> <u>Microcontrollers</u>"

Details

E·XFI

Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	20MHz
Connectivity	LINbus, UART/USART
Peripherals	Brown-out Detect/Reset, LCD, POR, PWM, WDT
Number of I/O	36
Program Memory Size	14KB (8K x 14)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	512 x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.6V
Data Converters	A/D 14x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	40-UFQFN Exposed Pad
Supplier Device Package	40-UQFN (5x5)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16lf1907t-i-mv

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong



FIGURE 3: 40-F	PIN PDIP PACKAGE DIA	AGRAM	FOR PIC16LF1904/7	
FIGURE 3: 40-F	VPP/MCLR/RE3 1 SEG12/AN0/RA0 2 SEG7/AN1/RA1 3 COM2/AN2/RA2 4 G15/VREF+/AN3/RA3 5 SEG4/T0CKI/RA4 6 SEG2/AN4/RA5 7 SEG21/AN5/RE0 8 SEG2/AN4/RA5 10 VDD 11 VSS 12 SEG2/AN6/RE1 9 SEG22/AN6/RE1 9 SEG22/AN6/RE1 10 VDD 11 VSS 12 SEG2/CLKIN/RA7 13 SEG1/CLKOUT/RA6 14 T1CKI/T10SO/RC0 15 T10SI/RC1 16 SEG3/RC2 17 SEG6/RC3 18 COM3/RD0 19 SEG27/RD1 20	AGRAM	40 RB7/ICSPDAT/ICDDAT/SEG13 39 RB6/ICSPCLK/ICDCLK/SEG14 38 RB5/AN13/COM1 37 RB4/AN11/COM0 36 RB3/AN9/SEG26/VLCD3 35 RB2/AN8/SEG25/VLCD2 34 RB1/AN10/SEG24/VLCD1 33 RB0/AN12/INT/SEG0 34 RD7/SEG20 35 RD7/SEG20 36 RD5/SEG18 37 RD4/SEG17 38 RC5/SEG10 39 RC5/SEG10 30 RC4/T1G/SEG11 31 RS2 32 RD4/SEG17	

FIGURE 5:	40-PIN UQFN (5X5) I	PACKAGE DIAGRAM FOR PIC16	6LF1904/7
		RC6/TX/CK/SEG9 RC5/SEG10 RC4/T16/SEG11 RD3/SEG16 RD2/SEG28 RD1/SEG27 RD0/COM3 RC3/SEG6 RC3/SEG6 RC2/SEG3 RC1/T1OS1	
	SEG8/DT/RX/RC7	1 337 337 337 337 338 333 337 337 337 337	
	SEG17/RD4 SEG18/RD5 SEG19/RD6 SEG20/RD7 VSS VDD SEG0/INT/AN12/RB0 VLCD1/SEG24/AN10/RB1 VLCD2/SEG25/AN8/RB2	2 30 F 3 29 F 4 28 F 5 27 V 6 PIC16LF1904/7 26 V 7 25 F 8 24 F 9 23 F 10 22 F 10 22 F 10 22 F	RC0/T10S0/T1CKI RA6/CLKOUT/SEG1 RA7/CLKIN/SEG2 /ss /pd RE2/AN7/SEG23 RE1/AN6/SEG22 RE0/AN5/SEG21 RA5/AN4/SEG5 RA4/T0CKI/SEG4
		VLCD3/SEG26/AN9/RB3 COM0/AN11/RB4 COM1/AN13/RB5 SEG14/ICDCLK/ICSPCLK/RB6 SEG13/ICDDAT/ICSPDAT/RB7 VPP/MCLR/RE3 SEG12/AN0/RA0 SEG12/AN1/RA1 COM2/AN1/RA1 COM2/AN1/RA1	

3.0 MEMORY ORGANIZATION

These devices contain the following types of memory:

- Program Memory
 - Configuration Words
 - Device ID
 - User ID
 - Flash Program Memory
- Data Memory
 - Core Registers
 - Special Function Registers
 - General Purpose RAM
 - Common RAM

The following features are associated with access and control of program memory and data memory:

- PCL and PCLATH
- Stack
- Indirect Addressing

TABLE 3-1: DEVICE SIZES AND ADDRESSES

Device Program Memory Space (Words)		Last Program Memory Address	High-Endurance Flash Memory Address Range ⁽¹⁾		
PIC16LF1904	4,096	0FFFh	0F80h-0FFFh		
PIC16LF1906/7	8,192	1FFFh	1F80h-1FFFh		

Note 1: High-endurance Flash applies to low byte of each address in the range.

3.1 Program Memory Organization

The enhanced mid-range core has a 15-bit program counter capable of addressing 32K x 14 program memory space. Table 3-1 shows the memory sizes implemented for the PIC16LF1904/6/7 family. Accessing a location above these boundaries will cause a wraparound within the implemented memory space. The Reset vector is at 0000h and the interrupt vector is at 0004h (see Figures 3-1, and 3-2).

3.3 PCL and PCLATH

The Program Counter (PC) is 15 bits wide. The low byte comes from the PCL register, which is a readable and writable register. The high byte (PC<14:8>) is not directly readable or writable and comes from PCLATH. On any Reset, the PC is cleared. Figure 3-4 shows the five situations for the loading of the PC.

FIGURE 3-4: LOADING OF PC IN DIFFERENT SITUATIONS



3.3.1 MODIFYING PCL

Executing any instruction with the PCL register as the destination simultaneously causes the Program Counter PC<14:8> bits (PCH) to be replaced by the contents of the PCLATH register. This allows the entire contents of the program counter to be changed by writing the desired upper seven bits to the PCLATH register. When the lower eight bits are written to the PCL register, all 15 bits of the program counter will change to the values contained in the PCLATH register.

3.3.2 COMPUTED GOTO

A computed GOTO is accomplished by adding an offset to the program counter (ADDWF PCL). When performing a table read using a computed GOTO method, care should be exercised if the table location crosses a PCL memory boundary (each 256-byte block). Refer to Application Note AN556, *"Implementing a Table Read"* (DS00556).

3.3.3 COMPUTED FUNCTION CALLS

A computed function CALL allows programs to maintain tables of functions and provide another way to execute state machines or look-up tables. When performing a table read using a computed function CALL, care should be exercised if the table location crosses a PCL memory boundary (each 256-byte block).

If using the CALL instruction, the PCH<2:0> and PCL registers are loaded with the operand of the CALL instruction. PCH<6:3> is loaded with PCLATH<6:3>.

The CALLW instruction enables computed calls by combining PCLATH and W to form the destination address. A computed CALLW is accomplished by loading the W register with the desired address and executing CALLW. The PCL register is loaded with the value of W and PCH is loaded with PCLATH.

3.3.4 BRANCHING

The branching instructions add an offset to the PC. This allows relocatable code and code that crosses page boundaries. There are two forms of branching, BRW and BRA. The PC will have incremented to fetch the next instruction in both cases. When using either branching instruction, a PCL memory boundary may be crossed.

If using BRW, load the W register with the desired unsigned address and execute BRW. The entire PC will be loaded with the address PC + 1 + W.

If using BRA, the entire PC will be loaded with PC + 1 +, the signed value of the operand of the BRA instruction.

5.1 Power-on Reset (POR)

The POR circuit holds the device in Reset until VDD has reached an acceptable level for minimum operation. Slow rising VDD, fast operating speeds or analog performance may require greater than minimum VDD. The PWRT, BOR or MCLR features can be used to extend the start-up period until all device operation conditions have been met.

5.1.1 POWER-UP TIMER (PWRT)

The Power-up Timer provides a nominal 64 ms time-out on POR or Brown-out Reset.

The device is held in Reset as long as PWRT is active. The PWRT delay allows additional time for the VDD to rise to an acceptable level. The Power-up Timer is enabled by clearing the PWRTE bit in Configuration Word 1.

The Power-up Timer starts after the release of the POR and BOR.

For additional information, refer to Application Note AN607, *"Power-up Trouble Shooting"* (DS00607).

5.2 Brown-Out Reset (BOR)

The BOR circuit holds the device in Reset when VDD reaches a selectable minimum level. Between the POR and BOR, complete voltage range coverage for execution protection can be implemented.

The Brown-out Reset module has four operating modes controlled by the BOREN<1:0> bits in Configuration Word 1. The four operating modes are:

- · BOR is always on
- · BOR is off when in Sleep
- · BOR is controlled by software
- · BOR is always off

Refer to Table 5-1 for more information.

The Brown-out Reset voltage level is selectable by configuring the BORV bit in Configuration Word 2.

A VDD noise rejection filter prevents the BOR from triggering on small events. If VDD falls below VBOR for a duration greater than parameter TBORDC, the device will reset. See Figure 5-2 for more information.

BOREN<1:0>	SBOREN	Device Mode	BOR Mode	Device Operation upon release of POR	Device Operation upon wake- up from Sleep	
11	Х	Х	Active	Waits for BOR ready ⁽¹⁾		
10	37	Awake	Active	Maita for	POP ready	
10	X	Sleep	Disabled	waits for i	BOR ready	
0.1	1	х	Active	Waits for BOR ready ⁽¹⁾		
UI	0	х	Disabled	Begins immediately		
00	X	х	Disabled	Begins immediately		

TABLE 5-1:BOR OPERATING MODES

Note 1: In these specific cases, "release of POR" and "wake-up from Sleep," there is no delay in start-up. The BOR ready flag, (BORRDY = 1), will be set before the CPU is ready to execute instructions because the BOR circuit is forced on by the BOREN<1:0> bits.

5.2.1 BOR IS ALWAYS ON

When the BOREN bits of Configuration Word 1 are set to '11', the BOR is always on. The device start-up will be delayed until the BOR is ready and VDD is higher than the BOR threshold.

BOR protection is active during Sleep. The BOR does not delay wake-up from Sleep.

5.2.2 BOR IS OFF IN SLEEP

When the BOREN bits of Configuration Word 1 are set to '10', the BOR is on, except in Sleep. The device start-up will be delayed until the BOR is ready and VDD is higher than the BOR threshold.

BOR protection is not active during Sleep. The device wake-up will be delayed until the BOR is ready.

5.2.3 BOR CONTROLLED BY SOFTWARE

When the BOREN bits of Configuration Word 1 are set to '01', the BOR is controlled by the SBOREN bit of the BORCON register. The device start-up is not delayed by the BOR ready condition or the VDD level.

BOR protection begins as soon as the BOR circuit is ready. The status of the BOR circuit is reflected in the BORRDY bit of the BORCON register.

BOR protection is unchanged by Sleep.

5.3 Low-Power Brown-out Reset (LPBOR)

The Low-Power Brown-Out Reset (LPBOR) is an essential part of the Reset subsystem. Refer to Figure 5-1 to see how the BOR interacts with other modules.

The LPBOR is used to monitor the external VDD pin. When too low of a voltage is detected, the device is held in Reset. When this occurs, a register bit ($\overline{\text{BOR}}$) is changed to indicate that a BOR Reset has occurred. The same bit is set for both the BOR and the LPBOR. Refer to Register 5-2.

5.3.1 ENABLING LPBOR

The LPBOR is controlled by the LPBOR bit of Configuration Word 2. When the device is erased, the LPBOR module defaults to disabled.

5.3.1.1 LPBOR Module Output

The output of the LPBOR module is a signal indicating whether or not a Reset is to be asserted. This signal is to be OR'd together with the Reset signal of the BOR module to provide the generic BOR signal, which goes to the PCON register and to the power control block.

5.4 MCLR

The $\overline{\text{MCLR}}$ is an optional external input that can reset the device. The $\overline{\text{MCLR}}$ function is controlled by the MCLRE bit of Configuration Word 1 and the LVP bit of Configuration Word 2 (Table 5-2).

TABLE 5-2: MCLR CONFIGURATION

MCLRE	LVP	MCLR
0	0	Disabled
1	0	Enabled
x	1	Enabled

5.4.1 MCLR ENABLED

When MCLR is enabled and the pin is held low, the device is held in Reset. The MCLR pin is connected to VDD through an internal weak pull-up.

The device has a noise filter in the $\overline{\text{MCLR}}$ Reset path. The filter will detect and ignore small pulses.

Note: A Reset does not drive the MCLR pin low.

5.4.2 MCLR DISABLED

When MCLR is disabled, the pin functions as a general purpose input and the internal weak pull-up is under software control. See **Section 11.5** "**PORTE Registers**" for more information.

5.5 Watchdog Timer (WDT) Reset

The Watchdog Timer generates a Reset if the firmware does not issue a CLRWDT instruction within the time-out period. The TO and PD bits in the STATUS register are changed to indicate the WDT Reset. See **Section 9.0** "**Watchdog Timer**" for more information.

5.6 RESET Instruction

A RESET instruction will cause a device Reset. The \overline{RI} bit in the PCON register will be set to '0'. See Table 5-4 for default conditions after a RESET instruction has occurred.

5.7 Stack Overflow/Underflow Reset

The device can reset when the Stack Overflows or Underflows. The STKOVF or STKUNF bits of the PCON register indicate the Reset condition. These Resets are enabled by setting the STVREN bit in Configuration Word 2. See **Section 5.7 "Stack Overflow/Underflow Reset"** for more information.

5.8 Programming Mode Exit

Upon exit of Programming mode, the device will behave as if a POR had just occurred.

5.9 Power-Up Timer

The Power-up Timer optionally delays device execution after a BOR or POR event. This timer is typically used to allow VDD to stabilize before allowing the device to start running.

The Power-up Timer is controlled by the $\overrightarrow{\text{PWRTE}}$ bit of Configuration Word 1.

5.10 Start-up Sequence

Upon the release of a POR or BOR, the following must occur before the device will begin executing:

- 1. Power-up Timer runs to completion (if enabled).
- 2. Oscillator start-up timer runs to completion (if required for oscillator source).
- 3. MCLR must be released (if enabled).

The total time-out will vary based on oscillator configuration and Power-up Timer configuration. See **Section 6.0 "Oscillator Module"** for more information.

The Power-up Timer and oscillator start-up timer run independently of MCLR Reset. If MCLR is kept low long enough, the Power-up Timer and oscillator start-up timer will expire. Upon bringing MCLR high, the device will begin execution immediately (see Figure 5-3). This is useful for testing purposes or to synchronize more than one device operating in parallel.

U-0	U-0	R/W-1/1	U-0	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	
—	_	ANSA5	—	ANSA3	ANSA2	ANSA1	ANSA0	
bit 7							bit 0	
Legend:								
R = Readable bit		W = Writable	bit	U = Unimplemented bit, read as '0'				
u = Bit is unchanged x = Bit is unknown			nown	-n/n = Value at POR and BOR/Value at all other Resets				
'1' = Bit is set		'0' = Bit is clea	ared					

REGISTER 11-4: ANSELA: PORTA ANALOG SELECT REGISTER

bit 7-6	Unimplemented: Read as '0'
bit 5	 ANSA5: Analog Select between Analog or Digital Function on pins RA5, respectively 0 = Digital I/O. Pin is assigned to port or digital special function. 1 = Analog input. Pin is assigned as analog input⁽¹⁾. Digital input buffer disabled.
bit 4	Unimplemented: Read as '0'
bit 3-0	 ANSA<3:0>: Analog Select between Analog or Digital Function on pins RA<3:0>, respectively 0 = Digital I/O. Pin is assigned to port or digital special function. 1 = Analog input. Pin is assigned as analog input⁽¹⁾. Digital input buffer disabled.

Note 1: When setting a pin to an analog input, the corresponding TRIS bit must be set to Input mode in order to allow external control of the voltage on the pin.

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on Page
ANSELA	—	—	ANSA5		ANSA3	ANSA2	ANSA1	ANSA0	96
LATA	LATA7	LATA6	LATA5	LATA4	LATA3	LATA2	LATA1	LATA0	95
OPTION_REG	WPUEN	INTEDG	TMR0CS	TMR0SE	PSA	PS<2:0>			130
PORTA	RA7	RA6	RA5	RA4	RA3	RA2	RA1	RA0	95
TRISA	TRISA7	TRISA6	TRISA5	TRISA4	TRISA3	TRISA2	TRISA1	TRISA0	95

TABLE 11-3: SUMMARY OF REGISTERS ASSOCIATED WITH PORTA

Legend: x = unknown, u = unchanged, - = unimplemented locations read as '0'. Shaded cells are not used by PORTA.

TABLE 11-4: SUMMARY OF CONFIGURATION WORD WITH PORTA

Name	Bits	Bit -/7	Bit -/6	Bit 13/5	Bit 12/4	Bit 11/3	Bit 10/2	Bit 9/1	Bit 8/0	Register on Page
	13:8	_	_	—	_	- CLKOUTEN		N<1:0>	_	20
CONFIGT	7:0	CP	MCLRE	PWRTE	WDTE<1:0>		_	FOSC	C<1:0>	39

Legend: — = unimplemented location, read as '0'. Shaded cells are not used by PORTA.

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on Page
LATD	LATD7	LATD6	LATD5	LATD4	LATD3	LATD2	LATD1	LATD0	104
PORTD	RD7	RD6	RD5	RD4	RD3	RD2	RD1	RD0	104
TRISD	TRISD7	TRISD6	TRISD5	TRISD4	TRISD3	TRISD2	TRISD1	TRISD0	104

TABLE 11-10: SUMMARY OF REGISTERS ASSOCIATED WITH PORTD⁽¹⁾

Legend: x = unknown, u = unchanged, - = unimplemented locations read as '0'. Shaded cells are not used by PORTD. Note 1: PIC16LF1904/7 only.

13.0 FIXED VOLTAGE REFERENCE (FVR)

The Fixed Voltage Reference (FVR) is a stable voltage reference, independent of VDD, with 1.024V or 2.048V selectable output levels. The output of the FVR can be configured as the FVR input channel on the ADC.

The FVR can be enabled by setting the FVREN bit of the FVRCON register.

13.1 Independent Gain Amplifiers

The output of the FVR supplied to the ADC is routed through two independent programmable gain amplifiers. Each amplifier can be configured to amplify the reference voltage by 1x or 2x, to produce the two possible voltage levels.

The ADFVR<1:0> bits of the FVRCON register are used to enable and configure the gain amplifier settings for the reference supplied to the ADC module. Reference **Section 15.0** "**Analog-to-Digital Converter** (**ADC**) **Module**" for additional information.

13.2 FVR Stabilization Period

When the Fixed Voltage Reference module is enabled, it requires time for the reference and amplifier circuits to stabilize. Once the circuits stabilize and are ready for use, the FVRRDY bit of the FVRCON register will be set. See **Section 22.0** "**Electrical Specifications**" for the minimum delay requirement.

FIGURE 13-1: VOLTAGE REFERENCE BLOCK DIAGRAM



TABLE 13-1:	PERIPHERALS REQUIRING THE FIXED VOLTAGE REFERENCE (FVR)
-------------	---

Peripheral	Conditions	Description
HFINTOSC	FOSC<2:0> = 100 and IRCF<3:0> = 000x	INTOSC is active and device is not in Sleep.
	BOREN<1:0> = 11	BOR always enabled.
BOR	BOREN<1:0> = 10 and BORFS = 1	BOR disabled in Sleep mode, BOR Fast Start enabled.
	BOREN<1:0> = 01 and BORFS = 1	BOR under software control, BOR Fast Start enabled.

R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1				
WPUEN	INTEDG	TMR0CS	TMR0SE	PSA		PS<2:0>					
bit 7							bit 0				
Legend:											
R = Readable	bit	W = Writable	bit	U = Unimplemented bit, read as '0'							
u = Bit is unch	anged	x = Bit is unk	nown	-n/n = Value at POR and BOR/Value at all other Re							
'1' = Bit is set		'0' = Bit is cle	ared								
bit 7	WPUEN: We	ak Pull-up Ena	ible bit								
	1 = All weak	1 = All weak pull-ups are disabled (except \overline{MCLR} , if it is enabled)									
	0 = weak put	II-ups are enab	lea by individu	ial wPUx latch	values						
DIT 6	INTEDG: Inte	errupt Edge Se									
	1 = Interrupt	on fising edge	of INT pin								
bit 5	TMR0CS: Tir	TMPACS: TimerO Clock Source Select bit									
Sito	1 = Transition	non T0CKI pin									
	0 = Internal ir	nstruction cycle	e clock (Fosc/4	4)							
bit 4	TMR0SE: Timer0 Source Edge Select bit										
	1 = Increment on high-to-low transition on T0CKI pin										
	0 = Incremen	it on low-to-hig	h transition on	T0CKI pin							
bit 3	PSA: Prescaler Assignment bit										
	1 = Prescale	r is not assigne	ed to the Timer	0 module							
hit 2.0	v = Prescaler is assigned to the Timerv module										
	Bit	Value Timer0	Rate								
	(000 1:2	2								
	(+ }								
	(011 1:1	6								
	1	1:3	32								

REGISTER 16-1: OPTION_REG: OPTION REGISTER

TABLE 10-1: SUMMART OF REGISTERS ASSOCIATED WITH TIMER	TABLE 16-1:	SUMMARY OF REGISTERS	ASSOCIATED WITH TIMERO
--	-------------	----------------------	------------------------

1:64

1:128

1:256

101

110 111

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on Page
INTCON	GIE PEIE TMR0IE INTE IOCIE TMR0IF INTF IOCIF							65	
OPTION_REG	WPUEN INTEDG TMR0CS TMR0SE PSA PS<2:0>								130
TMR0	Timer0 Module Register								128*
TRISA	TRISA7 TRISA6 TRISA5 TRISA4 TRISA3 TRISA2 TRISA1 TRISA0							95	

Legend: — = Unimplemented location, read as '0'. Shaded cells are not used by the Timer0 module.

* Page provides register information.

FIGURE 18-2: EUSART RECEIVE BLOCK DIAGRAM



The operation of the EUSART module is controlled through three registers:

- Transmit Status and Control (TXSTA)
- Receive Status and Control (RCSTA)
- Baud Rate Control (BAUDCON)

These registers are detailed in Register 18-1, Register 18-2 and Register 18-3, respectively.

For all modes of EUSART operation, the TRIS control bits corresponding to the RX/DT and TX/CK pins should be set to '1'. The EUSART control will automatically reconfigure the pin from input to output, as needed.

When the receiver or transmitter section is not enabled then the corresponding RX/DT or TX/CK pin may be used for general purpose input and output.

18.5.1.5 Synchronous Master Reception

Data is received at the RX/DT pin. The RX/DT pin output driver must be disabled by setting the corresponding TRIS bits when the EUSART is configured for synchronous master receive operation.

In Synchronous mode, reception is enabled by setting either the Single Receive Enable bit (SREN of the RCSTA register) or the Continuous Receive Enable bit (CREN of the RCSTA register).

When SREN is set and CREN is clear, only as many clock cycles are generated as there are data bits in a single character. The SREN bit is automatically cleared at the completion of one character. When CREN is set, clocks are continuously generated until CREN is cleared. If CREN is cleared in the middle of a character the CK clock stops immediately and the partial character is discarded. If SREN and CREN are both set, then SREN is cleared at the completion of the first character and CREN takes precedence.

To initiate reception, set either SREN or CREN. Data is sampled at the RX/DT pin on the trailing edge of the TX/CK clock pin and is shifted into the Receive Shift Register (RSR). When a complete character is received into the RSR, the RCIF bit is set and the character is automatically transferred to the two character receive FIFO. The Least Significant eight bits of the top character in the receive FIFO are available in RCREG. The RCIF bit remains set as long as there are un-read characters in the receive FIFO.

18.5.1.6 Slave Clock

Synchronous data transfers use a separate clock line, which is synchronous with the data. A device configured as a slave receives the clock on the TX/CK line. The TX/ CK pin output driver must be disabled by setting the associated TRIS bit when the device is configured for synchronous slave transmit or receive operation. Serial data bits change on the leading edge to ensure they are valid at the trailing edge of each clock. One data bit is transferred for each clock cycle. Only as many clock cycles should be received as there are data bits.

18.5.1.7 Receive Overrun Error

The receive FIFO buffer can hold two characters. An overrun error will be generated if a third character, in its entirety, is received before RCREG is read to access the FIFO. When this happens the OERR bit of the RCSTA register is set. Previous data in the FIFO will not be overwritten. The two characters in the FIFO buffer can be read, however, no additional characters will be received until the error is cleared. The OERR bit can only be cleared by clearing the overrun condition. If the overrun error occurred when the SREN bit is set and CREN is clear then the error is cleared by reading RCREG.

If the overrun occurred when the CREN bit is set then the error condition is cleared by either clearing the CREN bit of the RCSTA register or by clearing the SPEN bit which resets the EUSART.

18.5.1.8 Receiving 9-bit Characters

The EUSART supports 9-bit character reception. When the RX9 bit of the RCSTA register is set the EUSART will shift nine bits into the RSR for each character received. The RX9D bit of the RCSTA register is the ninth, and Most Significant, data bit of the top unread character in the receive FIFO. When reading 9-bit data from the receive FIFO buffer, the RX9D data bit must be read before reading the eight Least Significant bits from the RCREG.

18.5.1.9 Synchronous Master Reception Setup:

- 1. Initialize the SPBRGH, SPBRGL register pair for the appropriate baud rate. Set or clear the BRGH and BRG16 bits, as required, to achieve the desired baud rate.
- 2. Set the RX/DT and TX/CK TRIS controls to '1'.
- Enable the synchronous master serial port by setting bits SYNC, SPEN and CSRC. Disable RX/DT and TX/CK output drivers by setting the corresponding TRIS bits.
- 4. Ensure bits CREN and SREN are clear.
- 5. If using interrupts, set the GIE and PEIE bits of the INTCON register and set RCIE.
- 6. If 9-bit reception is desired, set bit RX9.
- 7. Start reception by setting the SREN bit or for continuous reception, set the CREN bit.
- 8. Interrupt flag bit RCIF will be set when reception of a character is complete. An interrupt will be generated if the enable bit RCIE was set.
- 9. Read the RCSTA register to get the ninth bit (if enabled) and determine if any error occurred during reception.
- 10. Read the 8-bit received data by reading the RCREG register.
- 11. If an overrun error occurs, clear the error by either clearing the CREN bit of the RCSTA register or by clearing the SPEN bit which resets the EUSART.

R/W-0/0	R/W-0/0	R/C-0/0	U-0	R/W-0/0	R/W-0/0	R/W-1/1	R/W-1/1			
LCDEN	SLPEN	WERR	_	- CS<1:0> LMUX<1:0>						
bit 7 bit 0										
Legend:										
R = Readable	e bit	W = Writable b	bit	U = Unimp	lemented bit, read	as '0'				
u = Bit is uncl	hanged	x = Bit is unkn	own	-n/n = Valu	e at POR and BOF	R/Value at all ot	her Resets			
'1' = Bit is set		'0' = Bit is clea	red	C = Only c	learable bit					
bit 7	LCDEN: LCD	Driver Enable	bit							
	1 = LCD drive	er module is ena	abled							
	0 = LCD drive	er module is dis	abled							
bit 6	SLPEN: LCD	Driver Enable i	n Sleep Mo	de bit						
	 1 = LCD driver module is disabled in Sleep mode 0 = LCD driver module is enabled in Sleep mode 									
bit 5	. WERR: LCD Write Failed Error bit									
	1 = LCDDATAn register written while the WA bit of the LCDPS register = 0 (must be cleared in									
	software)									
L:1 4		vrite error	. 1							
DIT 4		ted: Read as ()							
bit 3-2	CS<1:0>: Clo	CK Source Sele	Ct dits							
	00 = F0SC/25	(Timer1)								
	1x = LFINTO	SC (31 kHz)								
bit 1-0	LMUX<1:0>:	Commons Sele	ect bits							
	Maximum Number of Pixels									
	EMUX<1:0> Multiplex PIC16LF1906 PIC16LF1904/7 Bias									
	00	Static (CON	/0)	19	29	Static				
	01	1/2 (COM<1	:0>)	38	58	1/2 or 1/3				
	10	1/3 (COM<2	:0>)	57	87	1/2 or 1/3				
	11 1/4 (COM<3:0>) 72 ⁽¹⁾ 116 1/3									

REGISTER 19-1: LCDCON: LIQUID CRYSTAL DISPLAY (LCD) CONTROL REGISTER

Note 1: On these devices, COM3 and SEG15 are shared on one pin, limiting the device from driving 72 segments.



TABLE 22-2: SUPPLY CURRENT (IDD)^(1,2)

PIC16LF1	904/6/7	Standard Operating Conditions (unless otherwise stated)							
Param Device		_ .			Conditions				
No.	Characteristics	Min.	Тур†	Max.	Units	Vdd	Note		
	Supply Current (IDD) ^(1, 2)								
D010		_	58	75	μA	1.8	Fosc = 1 MHz		
		_	115	140	μA	3.0	EC Oscillator mode		
		—	133	176	μA	3.6	High Power mode		
D011		—	130	200	μA	1.8	Fosc = 4 MHz		
		_	245	300	μΑ	3.0	EC Oscillator mode		
		—	290	350	μA	3.6			
D012		_	218	275	μΑ	1.8	Fosc = 500 kHz		
		—	283	375	μA	3.0	HFINTOSC mode		
		—	314	395	μΑ	3.6			
D013		_	233	325	μA	1.8	Fosc = 1 MHz		
		—	309	425	μA	3.0	HFINTOSC mode		
		_	347	475	μA	3.6			
D014		_	305	360	μA	1.8	Fosc = 4 MHz		
			433	520	μA	3.0	HFINTOSC mode		
		_	500	600	μA	3.6			
D015		_	395	480	μA	1.8	Fosc = 8 MHz		
		_	600	720	μA	3.0	HFINTOSC mode		
		_	700	850	μA	3.6	-		
D016		_	567	670	μA	1.8	Fosc = 16 MHz		
		_	915	1100	μA	3.0	HFINTOSC mode		
		_	1087	1300	μA	3.6	-		
D017		_	2.7	7.2	μA	1.8	Fosc = 31 kHz		
		_	4.5	9.7	μA	3.0	LFINTOSC mode		
		_	5.2	12.0	μA	3.6	$-40^{\circ}C \le IA \le +125^{\circ}C$		
D017A		_	2.7	6.5	μA	1.8	Fosc = 31 kHz		
		_	4.5	9.0	μΑ	3.0	LFINTOSC mode		
		_	5.2	11.0	μA	3.6	$-40^{\circ}C \le TA \le +85^{\circ}C$		
D018		_	2.4	6.7	μA	1.8	Fosc = 32 kHz		
		_	4.2	9.2	μ Α	3.0	EC Oscillator mode, Low-Power mode		
		—	4.8	11.5	μA	3.6	$-40^{\circ}C \le TA \le +125^{\circ}C$		
D018A		1_	2.4	6.0	uА	1.8	Fosc = 32 kHz		
		—	4.2	8.5	μA	3.0	EC Oscillator mode, Low-Power mode		
		<u> </u>	4.8	10.5	μ Α	3.6	$-40^{\circ}C \le TA \le +85^{\circ}C$		
		1			,				

* These parameters are characterized but not tested.

† Data in "Typ" column is at 3.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: The test conditions for all IDD measurements in active operation mode are: OSC1 = external square wave, from rail-to-rail; all I/O pins tri-stated, pulled to VDD; MCLR = VDD; WDT disabled.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors, such as I/O pin loading and switching rate, oscillator type, internal code execution pattern and temperature, also have an impact on the current consumption.

3: FVR and BOR are disabled.

24.0 DEVELOPMENT SUPPORT

The PIC[®] microcontrollers (MCU) and dsPIC[®] digital signal controllers (DSC) are supported with a full range of software and hardware development tools:

- · Integrated Development Environment
- MPLAB[®] X IDE Software
- Compilers/Assemblers/Linkers
 - MPLAB XC Compiler
 - MPASM[™] Assembler
 - MPLINK[™] Object Linker/ MPLIB[™] Object Librarian
 - MPLAB Assembler/Linker/Librarian for Various Device Families
- · Simulators
 - MPLAB X SIM Software Simulator
- · Emulators
 - MPLAB REAL ICE™ In-Circuit Emulator
- In-Circuit Debuggers/Programmers
 - MPLAB ICD 3
 - PICkit™ 3
- Device Programmers
- MPLAB PM3 Device Programmer
- Low-Cost Demonstration/Development Boards, Evaluation Kits and Starter Kits
- Third-party development tools

24.1 MPLAB X Integrated Development Environment Software

The MPLAB X IDE is a single, unified graphical user interface for Microchip and third-party software, and hardware development tool that runs on Windows[®], Linux and Mac $OS^{®}$ X. Based on the NetBeans IDE, MPLAB X IDE is an entirely new IDE with a host of free software components and plug-ins for high-performance application development and debugging. Moving between tools and upgrading from software simulators to hardware debugging and programming tools is simple with the seamless user interface.

With complete project management, visual call graphs, a configurable watch window and a feature-rich editor that includes code completion and context menus, MPLAB X IDE is flexible and friendly enough for new users. With the ability to support multiple tools on multiple projects with simultaneous debugging, MPLAB X IDE is also suitable for the needs of experienced users.

Feature-Rich Editor:

- Color syntax highlighting
- Smart code completion makes suggestions and provides hints as you type
- Automatic code formatting based on user-defined rules
- · Live parsing

User-Friendly, Customizable Interface:

- Fully customizable interface: toolbars, toolbar buttons, windows, window placement, etc.
- · Call graph window
- Project-Based Workspaces:
- · Multiple projects
- Multiple tools
- · Multiple configurations
- · Simultaneous debugging sessions

File History and Bug Tracking:

- · Local file history feature
- Built-in support for Bugzilla issue tracker

24.2 MPLAB XC Compilers

The MPLAB XC Compilers are complete ANSI C compilers for all of Microchip's 8, 16, and 32-bit MCU and DSC devices. These compilers provide powerful integration capabilities, superior code optimization and ease of use. MPLAB XC Compilers run on Windows, Linux or MAC OS X.

For easy source level debugging, the compilers provide debug information that is optimized to the MPLAB X IDE.

The free MPLAB XC Compiler editions support all devices and commands, with no time or memory restrictions, and offer sufficient code optimization for most applications.

MPLAB XC Compilers include an assembler, linker and utilities. The assembler generates relocatable object files that can then be archived or linked with other relocatable object files and archives to create an executable file. MPLAB XC Compiler uses the assembler to produce its object file. Notable features of the assembler include:

- Support for the entire device instruction set
- Support for fixed-point and floating-point data
- Command-line interface
- · Rich directive set
- Flexible macro language
- MPLAB X IDE compatibility

24.3 MPASM Assembler

The MPASM Assembler is a full-featured, universal macro assembler for PIC10/12/16/18 MCUs.

The MPASM Assembler generates relocatable object files for the MPLINK Object Linker, Intel[®] standard HEX files, MAP files to detail memory usage and symbol reference, absolute LST files that contain source lines and generated machine code, and COFF files for debugging.

The MPASM Assembler features include:

- Integration into MPLAB X IDE projects
- User-defined macros to streamline assembly code
- Conditional assembly for multipurpose source files
- Directives that allow complete control over the assembly process

24.4 MPLINK Object Linker/ MPLIB Object Librarian

The MPLINK Object Linker combines relocatable objects created by the MPASM Assembler. It can link relocatable objects from precompiled libraries, using directives from a linker script.

The MPLIB Object Librarian manages the creation and modification of library files of precompiled code. When a routine from a library is called from a source file, only the modules that contain that routine will be linked in with the application. This allows large libraries to be used efficiently in many different applications.

The object linker/library features include:

- Efficient linking of single libraries instead of many smaller files
- Enhanced code maintainability by grouping related modules together
- Flexible creation of libraries with easy module listing, replacement, deletion and extraction

24.5 MPLAB Assembler, Linker and Librarian for Various Device Families

MPLAB Assembler produces relocatable machine code from symbolic assembly language for PIC24, PIC32 and dsPIC DSC devices. MPLAB XC Compiler uses the assembler to produce its object file. The assembler generates relocatable object files that can then be archived or linked with other relocatable object files and archives to create an executable file. Notable features of the assembler include:

- · Support for the entire device instruction set
- · Support for fixed-point and floating-point data
- Command-line interface
- · Rich directive set
- Flexible macro language
- MPLAB X IDE compatibility



44-Lead Plastic Thin Quad Flatpack (PT) - 10x10x1.0 mm Body [TQFP]

Microchip Technology Drawing C04-076C Sheet 1 of 2

APPENDIX A: DATA SHEET REVISION HISTORY

Revision A (03/2011)

Original release.

Revision B (08/2014)

Added Tables 9-3 and 9-4.

Updated PIC16LF190X Family Types Table.

Updated Equation 15-1; Example 3-2; Figures 1 through 5, 6-4, 15-1, 15-4, 19-7 22-2, 22-8; Registers 4-1, 4-2, 11-17, 15-1; Sections 4.1, 6.2.2.2, 10.0, 13.0, 15.1.3, 18.1.1.2, 18.1.1.3, 18.1.1.7, 18.1.2.9, 18.1.2.10, 18.2, 18.4.1.2, 19.1, 19.4.5, 22.0, 22.1, 22.5, 22.6, 22.7, 22-8, 22-10; Tables 1, 3-1, 3-3, 3-5, 5-1, 9-2, 10-3, 10-4, 17-2, 19-1, 22-2, 22-3, 22-4, 22-5, 22-6, 22-7, 22-8, 22-12.

Updated Package Marking Information.

Removed Section 18.1.2.3: Receive Data Polarity and Section 18.4.1.4: Data Polarity.

Data sheet went from Preliminary to Final data sheet.

Revision C (01/2016)

Added 'Memory' section and updated the 'PIC16LF190X Family Types' table; Other minor corrections.

Revision D (05/2016)

Minor changes to Figure 22-2, Table 22-8, and Table 22-10, in Electrical Specifications chapter; Updated Packaging: 28L SOIC, 44L TQFP, 28L UQFN, 40L UQFN. Removed Table 19-7, LCD Worksheet.